

FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT	ATTY DOCKET NO. 50439-2	SERIAL NO. 09/605,442
APPLICANT(S): Barstad et al.		
FILING DATE: June 28, 2000		ART UNIT: 1741

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PATENT & TRADEMARK OFFICE

## UNITED STATES PATENT DOCUMENTS

EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
MM.	AA	5,252,196	10/12/93	Sonnenberg et al.			
	AB	3,770,598	11/06/73	Creutz			
↓	AC	3,784,454	01/08/74	Lyde			
MM.	AD	4,347,108	08/31/82	Willis			

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN YES/NO

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## OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)


Examiner: *Mayo* Date: 8/27/02

Sheet 1 of 1

FORM PTO-1449  INFORMATION DISCLOSURE STATEMENT		ATTY DOCKET NO. 50439	SERIAL NO. 09/313,045
		APPLICANT(S): Barstad et al.	
		FILING DATE: May 17, 1999	ART UNIT: 1741

## UNITED STATES PATENT DOCUMENTS

EXAM. INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
AA	3,876,513	04/08/75	Brown et al.			
AB	4,098,656	07/04/78	Deubor			
AC	4,530,741	07/23/85	Rosenberg			
AD	4,913,787	04/03/90	Kiso			
AE	5,051,154	09/24/91	Bernards et al.			
AF	5,068,013	11/26/91	Bernards et al.			
AG	5,174,886	12/29/92	King et al.			
AH	5,223,118	06/29/93	Sonnenberg et al.			
AJ	5,858,870	01/12/99	Zheng et al.			
AK	5,433,840	07/95	Dahms et al.			
AL	2,424,887	07/47	Henricks			
AM	5,151,170	09/92	Montgomery et al.			
AN	4,347,108	08/82	Willis			
AO	4,336,114	06/82	Mayer et al.			
AP	4,036,710	07/77	Kardos et al.			
AQ	6,113,771	09/00	Landau et al.			
AR	5,868,013	11/91	Bernards et al.			
AS	5,051,154	09/91	Bernards et al.			
AT	6,024,857	02/00	Reid			

## OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

BA	Shipley Advance Interconnect, Advanced Interconnect Materials, "Nanoplate™ Copper Plating Electrolyte Optimized for 200 nm, Bottom-up Trench Fill" Shipley Company, L.L.C. data sheet.
Examiner:	Date: